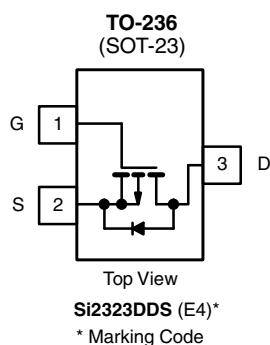


P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$R_{DS(on)}$ (Ω) Max.	I_D (A) ^d	Q_g (Typ.)
- 20	0.039 at $V_{GS} = - 4.5$ V	- 5.3	13.6 nC
	0.050 at $V_{GS} = - 2.5$ V	- 4.7	
	0.075 at $V_{GS} = - 1.8$ V	- 3.8	



Ordering Information:

Si2323DDS-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

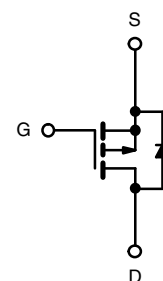
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- Material categorization:
For definitions of compliance please see
www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load Switch
- PA Switch
- DC/DC Converters
- Power Management



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	- 20	V
Gate-Source Voltage	V_{GS}	± 8	
Continuous Drain Current ($T_J = 150$ °C)	$T_C = 25$ °C	- 5.3	A
	$T_C = 70$ °C	- 4.3	
	$T_A = 25$ °C	- 4.1 ^{a,b}	
	$T_A = 70$ °C	- 3.2 ^{a,b}	
Pulsed Drain Current ($t = 300$ μ s)	I_{DM}	- 20	
Continuous Source-Drain Diode Current	$T_C = 25$ °C	- 1.4	
	$T_A = 25$ °C	- 0.8 ^{a,b}	
Maximum Power Dissipation	$T_C = 25$ °C	1.7	W
	$T_C = 70$ °C	1.1	
	$T_A = 25$ °C	0.96 ^{a,b}	
	$T_A = 70$ °C	0.62 ^{a,b}	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	°C

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{a, c}	t ≤ 5 s	R _{thJA}	100	130	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. $t = 5$ s.

c. Maximum under steady state conditions is 175 °C/W.

d. $T_C = 25$ °C.

SPECIFICATIONS ($T_J = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

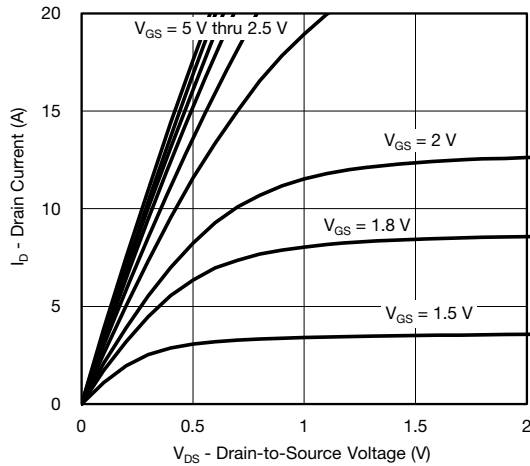
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 20			V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	I _D = - 250 μA		- 13		mV/°C
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)} /T _J			- 2.8		
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = - 250 μA	- 0.4		- 1	V
Gate-Source Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μA
		V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C			- 10	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≤ - 5 V, V _{GS} = - 4.5 V	- 15			A
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 4.1 A		0.032	0.039	Ω
		V _{GS} = - 2.5 V, I _D = - 2 A		0.041	0.050	
		V _{GS} = - 1.8 V, I _D = - 1 A		0.058	0.075	
Forward Transconductance ^a	g _{fs}	V _{DS} = - 10 V, I _D = - 4.1 A		18		S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		1160		pF
Output Capacitance	C _{oss}			135		
Reverse Transfer Capacitance	C _{rss}			120		
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 8 V, I _D = - 4.1 A		24	36	nC
Total Gate Charge	Q _g	V _{DS} = - 10 V, V _{GS} = - 4.5 V, I _D = - 4.1 A		13.6	21	
Gate-Source Charge	Q _{gs}			2		
Gate-Drain Charge	Q _{gd}			2.2		
Gate Resistance	R _g		f = 1 MHz	2	10	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 3.1 Ω I _D ≅ - 3.2 A, V _{GEN} = - 4.5 V, R _g = 1 Ω		24	36	ns
Rise Time	t _r			22	40	
Turn-Off Delay Time	t _{d(off)}			52	78	
Fall Time	t _f			11	20	
Turn-On Delay Time	t _{d(on)}	V _{DD} = - 10 V, R _L = 3.1 Ω I _D ≅ - 3.2 A, V _{GEN} = - 8 V, R _g = 1 Ω		8	16	
Rise Time	t _r			9	18	
Turn-Off Delay Time	t _{d(off)}			58	87	
Fall Time	t _f			9	18	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 1.4	A
Pulse Diode Forward Current	I _{SM}				- 20	
Body Diode Voltage	V _{SD}	I _S = - 3.2 A, V _{GS} = 0 V		- 0.79	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	I _F = - 3.2 A, dI/dt = 100 A/μs, T _J = 25 °C		14	25	ns
Body Diode Reverse Recovery Charge	Q _{rr}			6	12	nC
Reverse Recovery Fall Time	t _a			8		ns
Reverse Recovery Rise Time	t _b			6		

Notes:

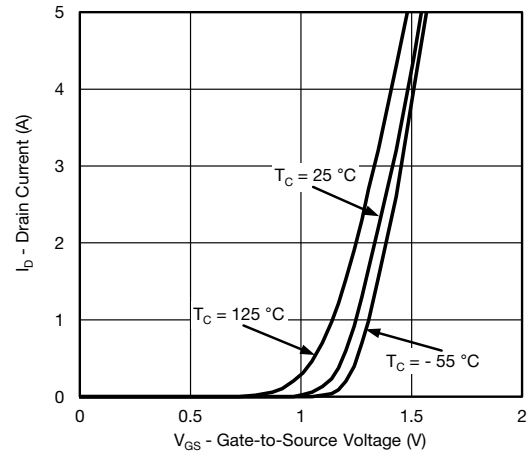
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

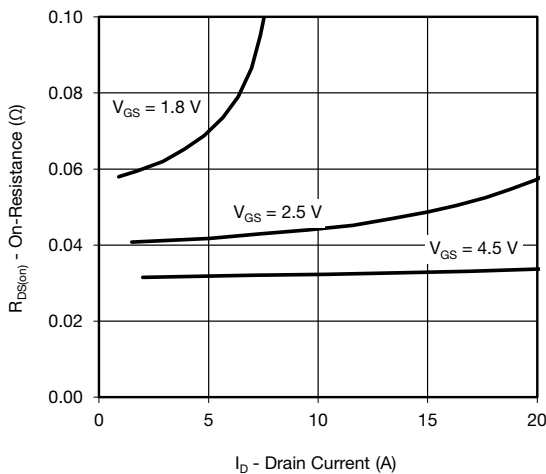
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



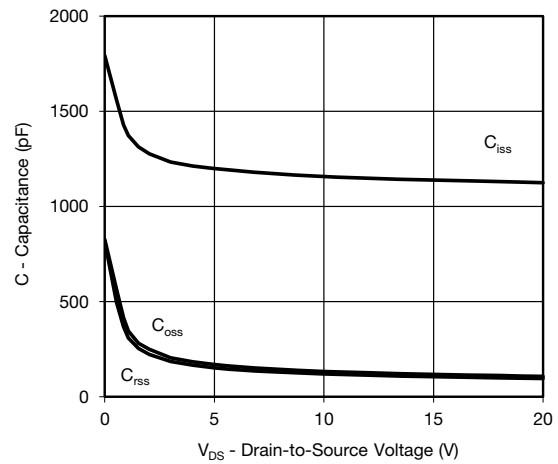
Output Characteristics



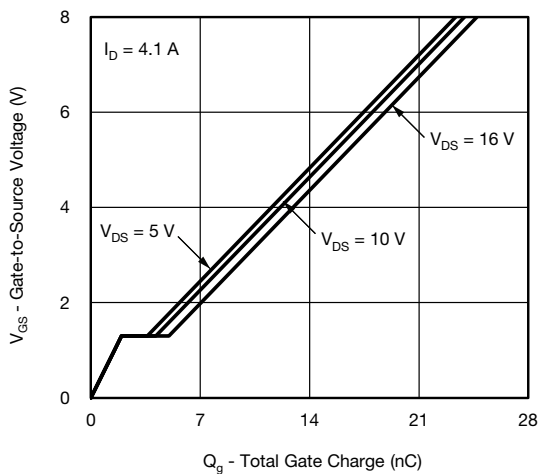
Transfer Characteristics



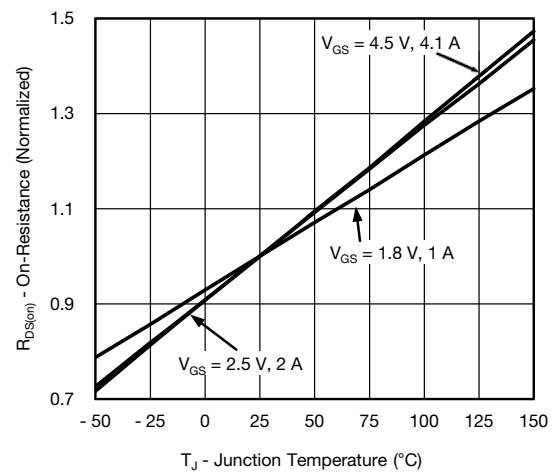
On-Resistance vs. Drain Current and Gate Voltage



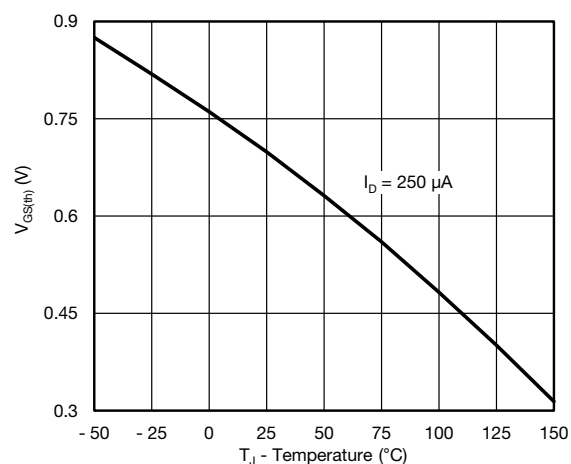
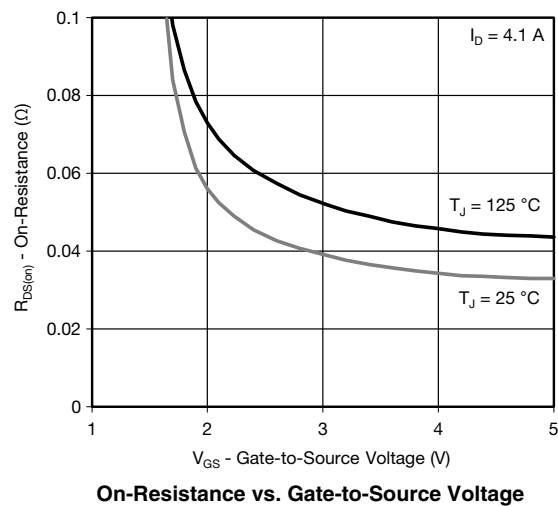
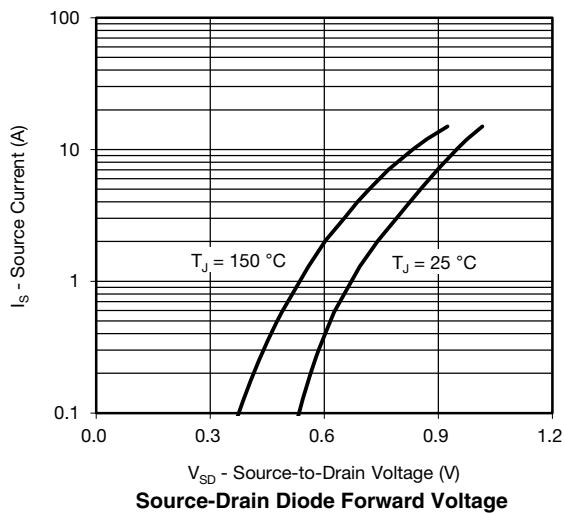
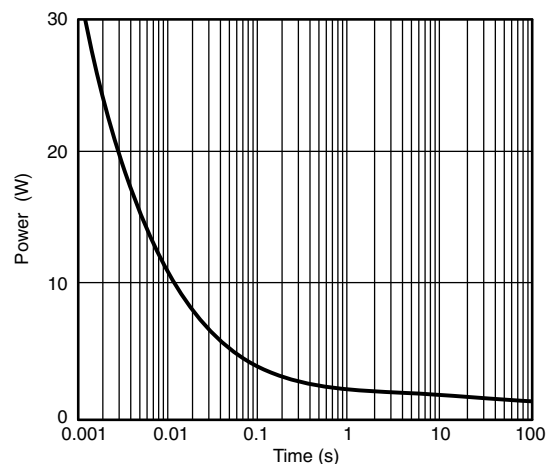
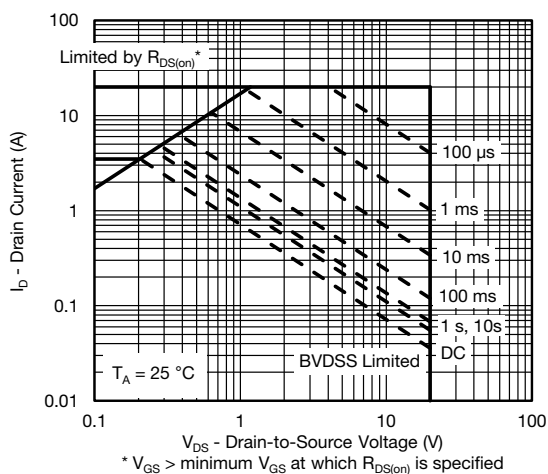
Capacitance



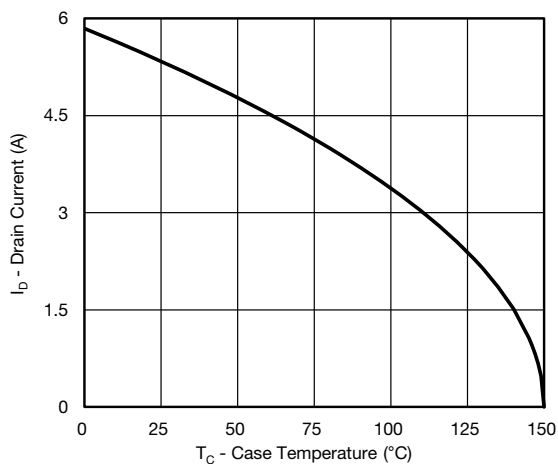
Gate Charge



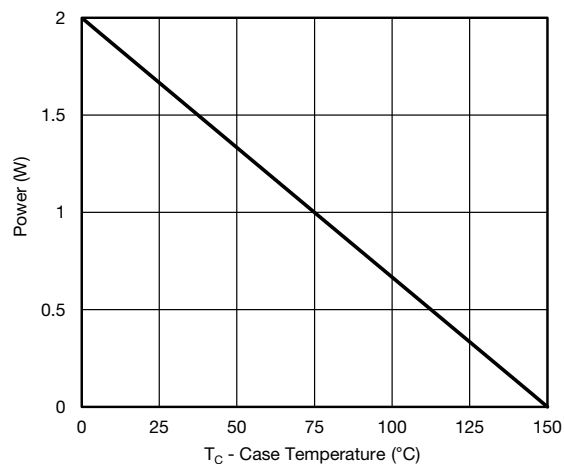
On-Resistance vs. Junction Temperature

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)**Threshold Voltage****Single Pulse Power, Junction-to-Ambient****Safe Operating Area, Junction-to-Ambient**

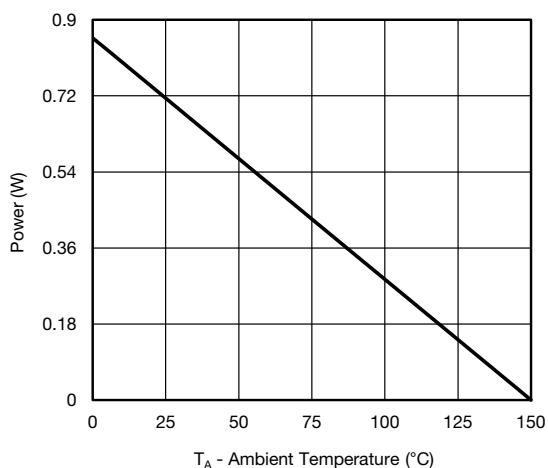
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*

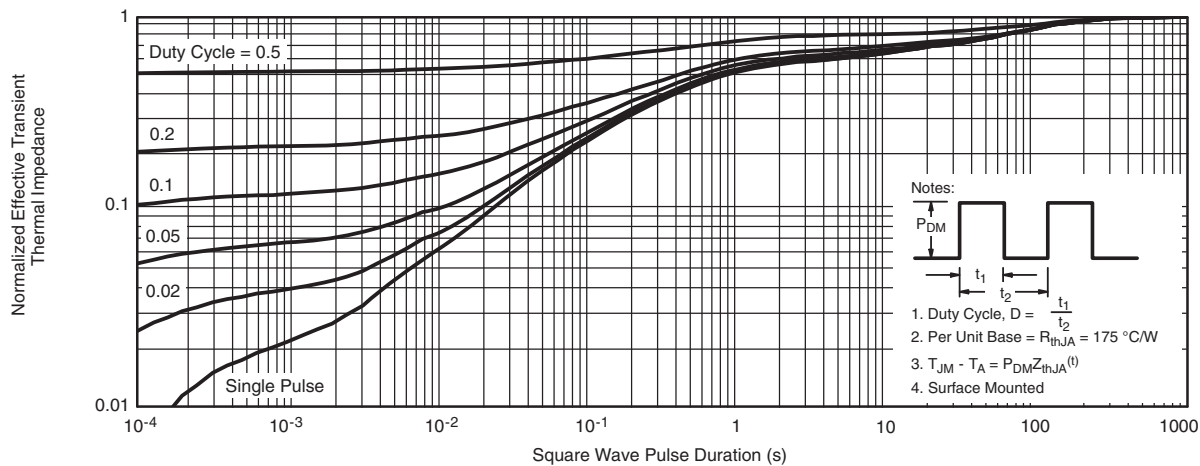
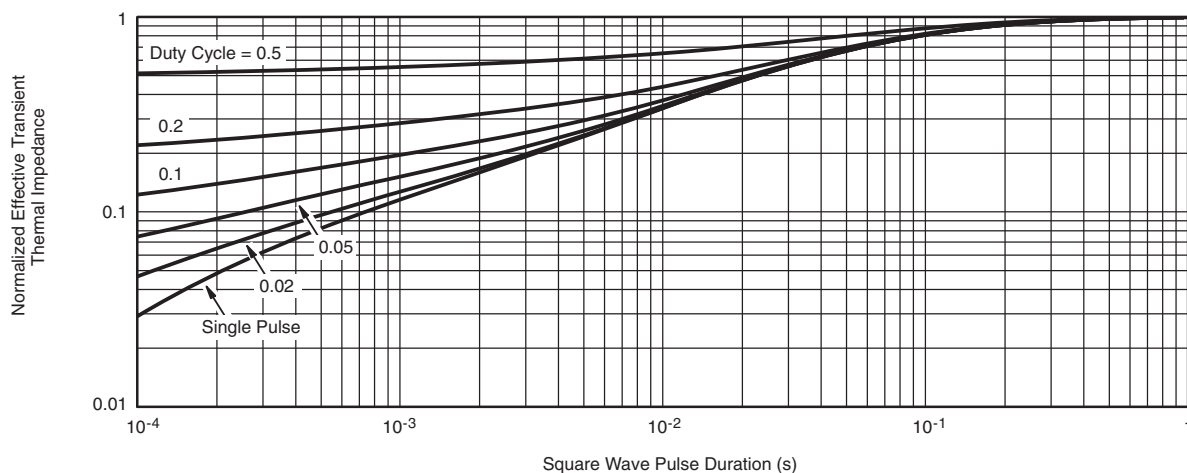


Power Derating, Junction-to-Foot



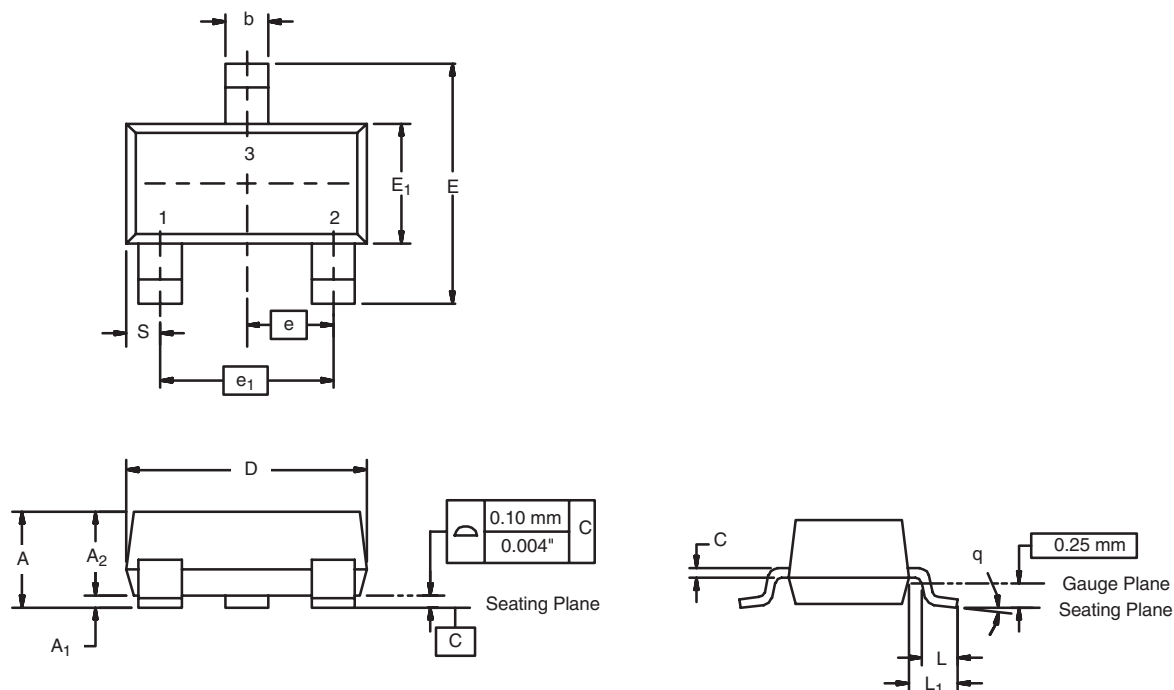
Power, Junction-to-Ambient

* The power dissipation P_D is based on $T_{J(max)} = 150\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)**Normalized Thermal Transient Impedance, Junction-to-Ambient****Normalized Thermal Transient Impedance, Junction-to-Foot**

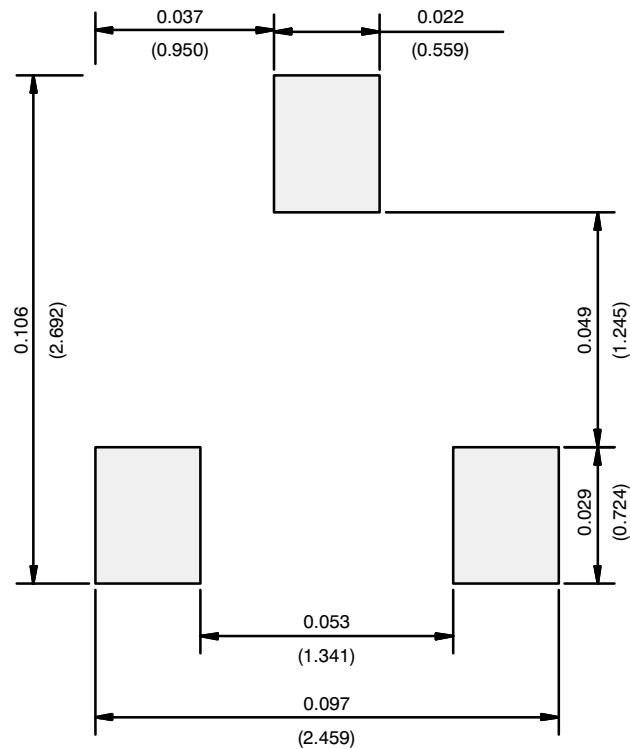
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SOT-23 (TO-236): 3-LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	0.89	1.12	0.035	0.044
A ₁	0.01	0.10	0.0004	0.004
A ₂	0.88	1.02	0.0346	0.040
b	0.35	0.50	0.014	0.020
c	0.085	0.18	0.003	0.007
D	2.80	3.04	0.110	0.120
E	2.10	2.64	0.083	0.104
E ₁	1.20	1.40	0.047	0.055
e	0.95 BSC		0.0374 Ref	
e ₁	1.90 BSC		0.0748 Ref	
L	0.40	0.60	0.016	0.024
L ₁	0.64 Ref		0.025 Ref	
S	0.50 Ref		0.020 Ref	
q	3°	8°	3°	8°
ECN: S-03946-Rev. K, 09-Jul-01 DWG: 5479				

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads
Dimensions in Inches/(mm)

[Return to Index](#)



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